ASSOCIATION CONNECT	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier Infor	mation								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2024-04-20			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Reque	ester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Manufacturing Site		eight*	UOM	Unit Type
	FDPC8014AS PT9N 30/12 & F		PT9N 30/12 & PT9	N 25/12	2024-04-20		PBB		12	1.566	mg	Each		
	g Process Informati										_			
			<u> </u>		STD-020 MSL	_ Rating	Peak Process Body Temper						er of Reflow Cyc	eles
	Tin (Sn) - annealed	C	U Alloy	1			260		С	30	seconds	3		
omments														
	n time at peak temperatur													
or more informa	ation regarding material c	omposition p	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the control of	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.025	mg
			Supplier	Iron (Fe)	7439-89-6		0.458	mg
			Supplier	Copper (Cu)	7440-50-8		18.617	mg
Die	1.6	mg	Supplier	Silicon (Si)	7440-21-3		1.6	mg
Die Attach Solder	1.936	mg	Supplier	Silver (Ag)	7440-22-4		0.0484	mg
			A	Lead (Pb)	7439-92-1	7a	1.7908	mg
			Supplier	Tin (Sn)	7440-31-5		0.0968	mg
Lead Frame	46.396	mg	Supplier	Silver (Ag)	7440-22-4		0.636	mg
			Supplier	Zinc (Zn)	7440-66-6		0.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.1	mg
			Supplier	Copper (Cu)	7440-50-8		44.6	mg
Mold Compound-Black	43.59	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.18	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.1	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.31	mg
Plating	8.33	mg	Supplier	Tin (Sn)	7440-31-5		8.33	mg
Wire Bond	0.614	mg	Supplier	Gold (Au)	7440-57-5		0.581	mg
			Supplier	Copper (Cu)	7440-50-8		0.033	mg